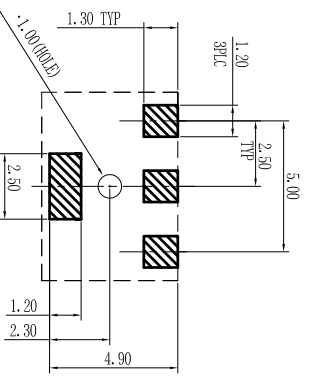
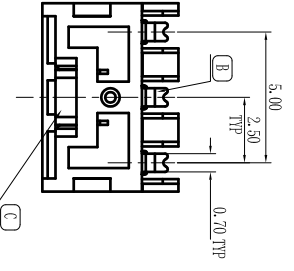
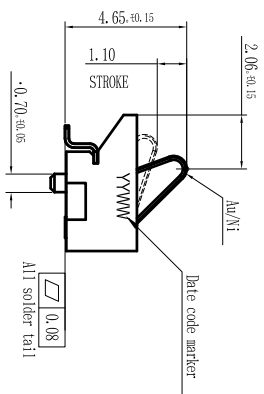
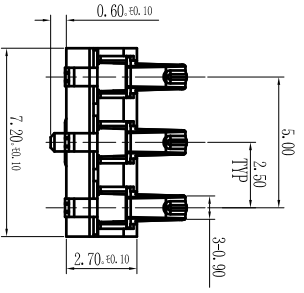
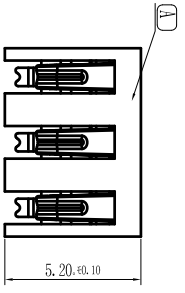
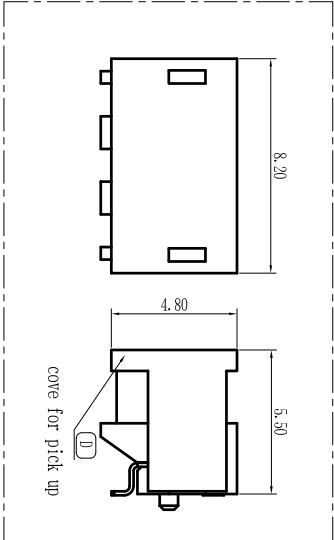
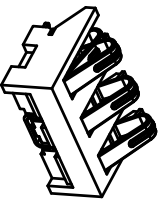


REV.	ECN NO OR DESCRIPTION	REVISED	DATE
A	PRODUCT RELEASE	SITONG HR	10/07/28



RECOMMENDED PCB BOARD LAYOUT
TOP VIEW(TOLERANCE: ±0.05)

- NOTE:
- 1.MATERIAL:
HOUSING:HIGH TEMP. THERMAL PLASTIC,UL94V-0,COLOR BLACK.
COVER:HIGH TEMP. THERMAL PLASTIC,UL94V-0,COLOR BLACK.
TERMINAL:COPPER ALLOY,T=0.15mm;
FORK: COPPER ALLOY,T=0.15mm.
- 2.FINISH:
TERMINAL:5u" MIN GOLD PLATING ON CONTACT AREA;
GOLD FLASH MIN GOLD PLATING ON OTHER AREAS;
60u" MIN NICKEL UNDERPLATING OVERALL.
FORK:120u" MIN BRIGHT TIN PLATING ALLOYER;
60u" MIN NICKEL UNDERPLATING OVERALL.
3. SPECIFICATION:SEE 2.5mm BATTERY 2.7H PRODUCT SPEC.
4. SOLDER HEAT RESISTANCE: REFLOW SOLDERING 260° FOR 10SEC.
5. TO CONFORM TO SINGATRON HAZARDOUS SUBSTANCE FREE SPEC.
6. HALOGEN PRODUCT IDENTIFICATION MARK ON JACK.◎
7. HALOGEN PRODUCT IDENTIFICATION LABEL ON PACKAGING.
8. FOR REFLOW SOLDERING LEED FREE PROCESS.
9. DATE CODE:
YYMM
Year Year



D	COVER	1	HIGH TEMP. THERMAL PLASTIC	SEE NOTE
C	FORK	1	COPPER ALLOY,0.15T	SEE NOTE
B	TERMINAL	3	COPPER ALLOY,0.15T	SEE NOTE
A	HOUSING	1	HIGH TEMP. THERMAL PLASTIC	COLOR BLACK
NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR

UNLESS OTHERWISE SPECIFIED TOLERANCES

Singatron Enterprise Co., Ltd.

DECIMALS:	ANGLES:	TITLE	2.5mm BATTERY 3P 2.7H SMT TYPE
X : ±0.5	X : ±2°	DRAWN	28A2013-000111
X.X : ±0.3	X.X : ±1°	CHKD	SCALE 4:1 UNIT: mm
X.XX : ±0.2		APVD	SIZE: A3 SHEET: 10P1 REV: A

CUSTOMER COPY